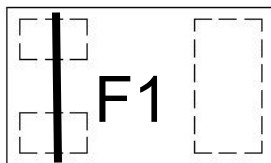
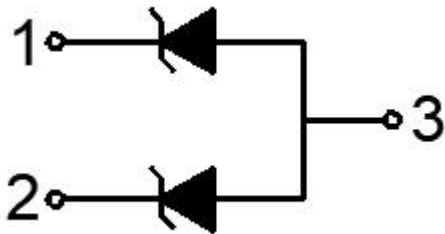
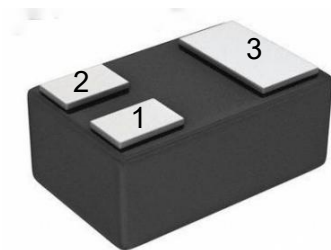


Features

- 3-pin lead-less package
- Low junction capacitance (Typical value: 0.8pF)
- Peak Pulse Current (8/20 μ s) : 5A
- IEC61000-4-2 (ESD) $\pm$ 15kV (air), $\pm$ 20kV (contact)
- Low clamping voltage
- Low leakage current
- Working voltages:5V
- RoHS Compliant

Appearance & Symbo



F1 = Marking Code

Mechanica Characteristics

- Package: DFN1006-3L
- Lead Finish:Matte Tin
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Tape Reel :10000pcs

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation,Digital Cameras ,Peripherals
- Audio Players,Keypads, Side Keys, USB 2.0, LCD Displays

Absolute Maximum Ratings (T=25°C, RH=45%-75%, unless otherwi

Parameters	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	75	W
Peak Pulse Current (8/20μs)	I _{PP}	5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±15 ±20	KV
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C, RH=45%-75%, unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V _{RWM}				5	V
Reverse Breakdown Voltage	V _{BR}	I _R = 1mA	6		9	V
Reverse Leakage Current	I _R	V _R = 5V			0.2	uA
Clamping Voltage	V _C	I _{PP} = 1A, T _P =8/20us, pin 1 or pin 2 to pin 3			10	V
Clamping Voltage	V _C	I _{PP} = 5A, T _P =8/20us, pin 1 or pin 2 to pin 3			15	V
Junction Capacitance	C _J	V _R = 0V, f = 1MHz, between pin 1 and pin 2		0.4	0.6	pF
Junction Capacitance	C _J	V _R = 0V, f = 1MHz, pin 1 or pin 2 to pin 3		0.8		pF

Typical Characteristics

FIG1: Power rating derating curve

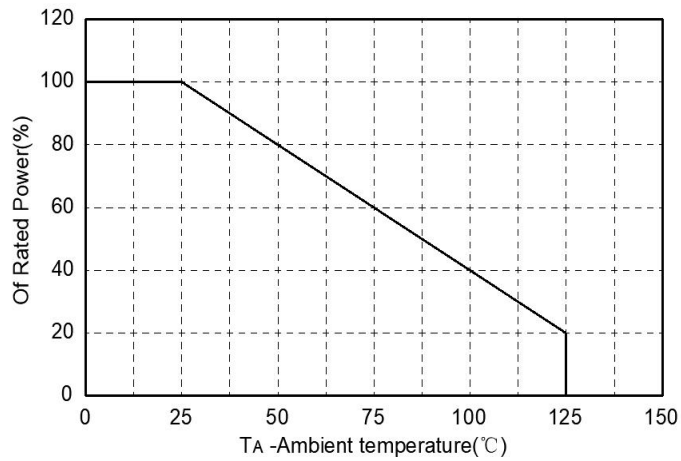


FIG2: pulse Waveform

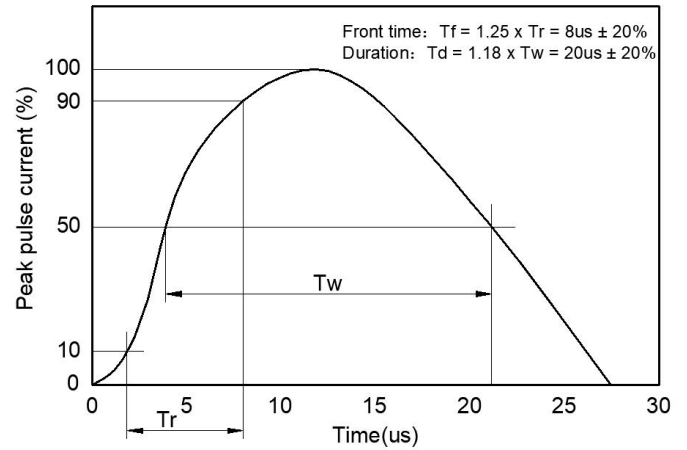


FIG3: Capacitance between terminals characteristics

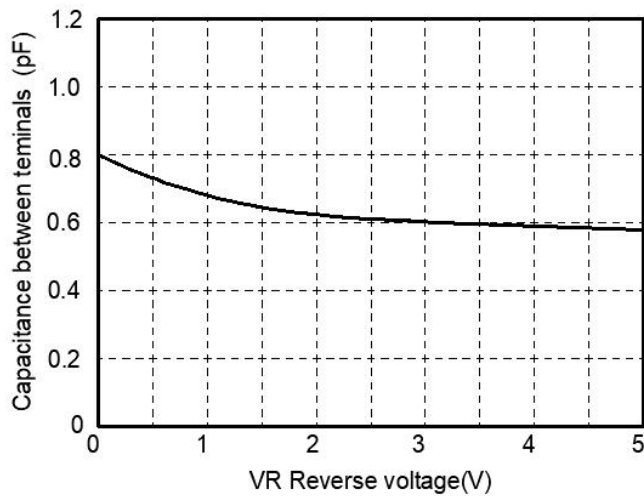
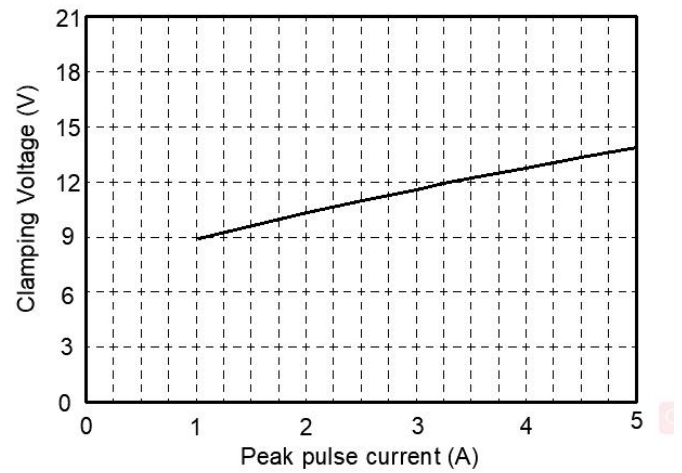
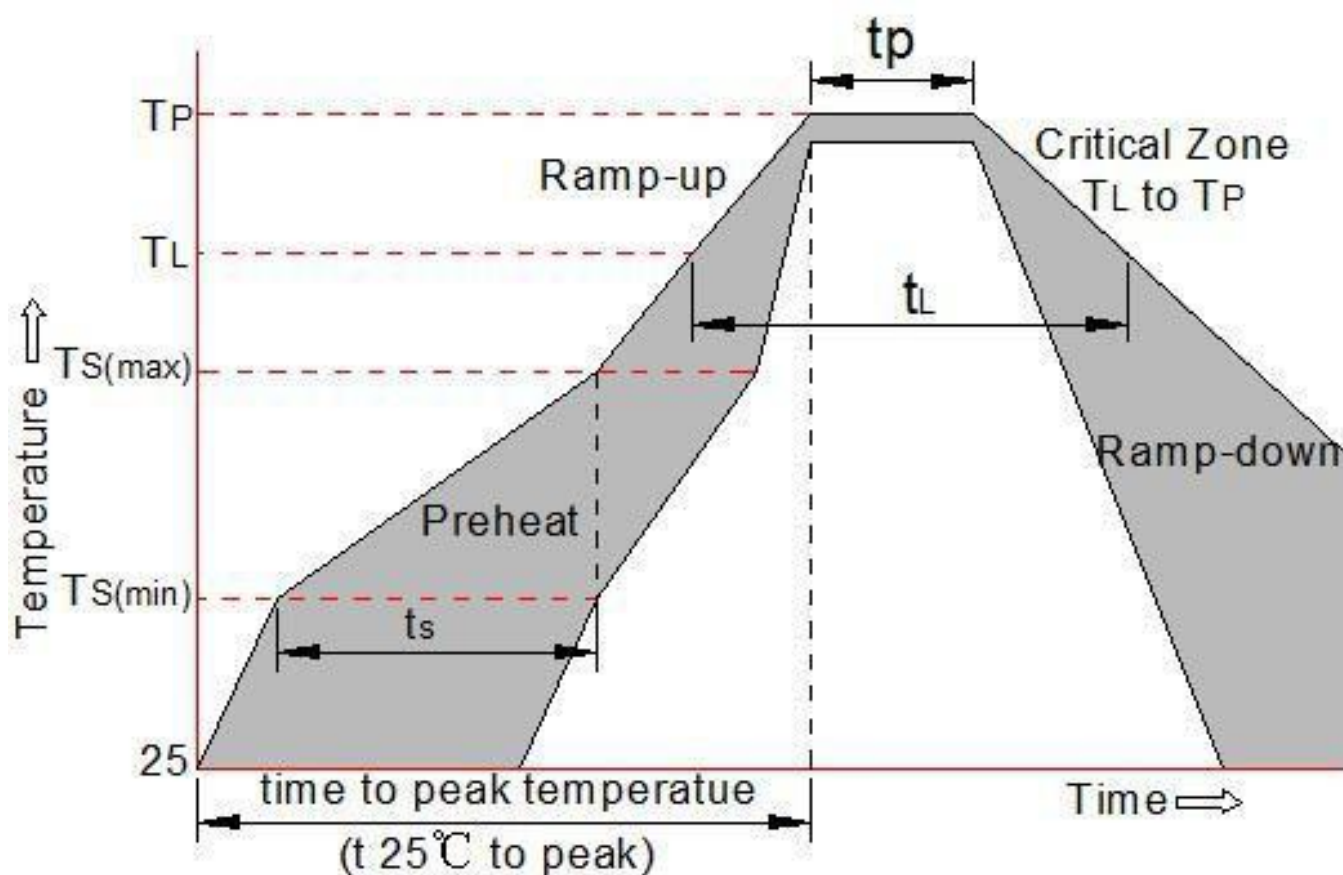


FIG4: Clamping Voltage vs. Peak Pulse Current

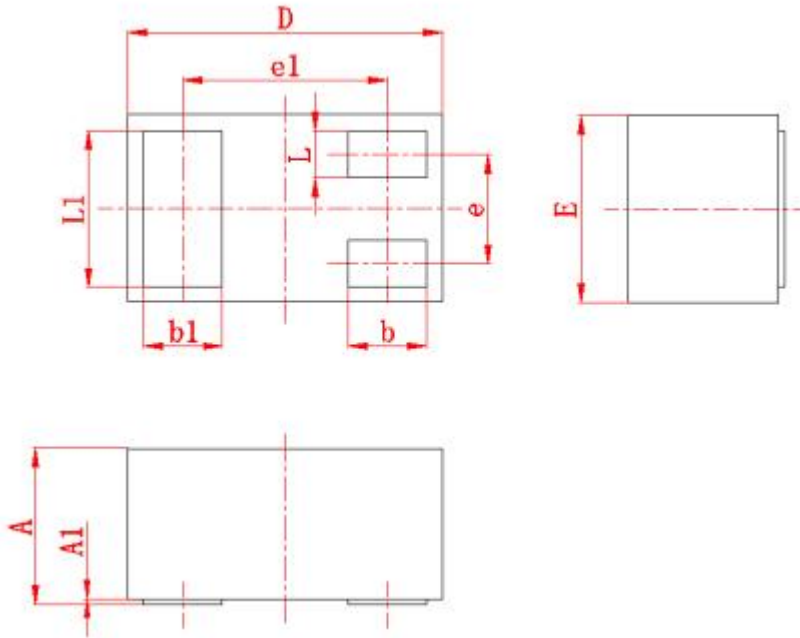


Soldering parameters

Reflow Condition		Pb-Free assembly see as bellow
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

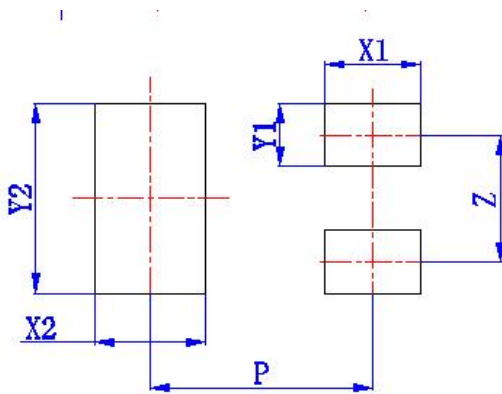


Package mechanical data



Symbol	Dimension in Millimeters	
	min	max
A	0.4	0.5
A1	0	0.05
D	0.9	1.1
E	0.55	0.65
e	(0.35)	
e1	(0.65)	
b	0.2	0.3
b1	0.2	0.3
L	0.1	0.2
L1	0.45	0.55

Suggested Land Pattern



Symbol	Dimension in Millimeters	
	typ	
X1	(0.3)	
X2	(0.35)	
Y1	(0.2)	
Y2	(0.6)	
Z	(0.4)	
P	(0.7)	